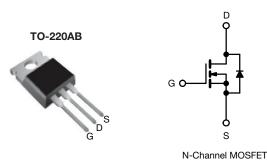
Vishay Siliconix

E Series Power MOSFET



PRODUCT SUMMA	RY	
V _{DS} (V) at T _J max.	850)
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 \text{ V}$	0.25
Q _g max. (nC)	122	2
Q _{gs} (nC)	14	
Q _{gd} (nC)	23	
Configuration	Sing	le

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>



APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-220AB
Load (Dh) free and halogen free	SiHP17N80E-BE3
Lead (Pb)-free and halogen-free	SiHP17N80E-GE3

ABSOLUTE MAXIMUM RATINGS (To	c = 25 °C, unl	ess otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			V_{DS}	800	V
Gate-source voltage		V_{GS}	± 30	v	
Continuous drain surrent (T. 150 °C)	V at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$		15	
Continuous drain current (T _J = 150 °C)	V _{GS} at 10 V	T _C = 100 °C	I _D	10	Α
Pulsed drain current ^a			I _{DM}	45	
Linear derating factor				1.7	W/°C
Single pulse avalanche energy b			E _{AS}	353	mJ
Maximum power dissipation			P_{D}	208	W
Operating junction and storage temperature range	,		T _J , T _{stg}	-55 to +150	°C
Drain-source voltage slope	$T_{J} = 1$	125 °C	d\//d+	70	V/ns
Reverse diode dV/dt d 5.1		V/ns			
Soldering recommendations (peak temperature) ^c	For	10 s		300	°C

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 140 V, starting T_J = 25 °C, L = 28.2 mH, R_q = 25 Ω , I_{AS} = 5.0 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, $dI/dt = 100 \text{ A/}\mu\text{s}$, starting $T_J = 25 \,^{\circ}\text{C}$



Vishay Siliconix

THERMAL RESISTANCE RATI	NGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R _{thJA}	-	62	°C/W
Maximum junction-to-case (drain)	R _{thJC}	-	0.6	G/ VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		-					•
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		800	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D = 1 mA	1	1.08	-	V/°C
Gate-source threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.0	-	4.0	V
		$V_{GS} = \pm 20 \text{ V}$		ı	-	± 100	nA
Gate-source leakage	I _{GSS}		$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
7		V _{DS} =	$V_{DS} = 800 \text{ V}, V_{GS} = 0 \text{ V}$		-	1	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 640 \	/, V _{GS} = 0 V, T _J = 125 °C	-	-	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 8.5 A	ı	0.25	0.29	Ω
Forward transconductance	9 _{fs}	V_{DS}	= 30 V, I _D = 8.5 A	-	8.7	-	S
Dynamic		•					
Input capacitance	C _{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ f = 1 MHz		-	2408	-	pF
Output capacitance	C _{oss}			1	81	-	
Reverse transfer capacitance	C _{rss}			-	9	-	
Effective output capacitance, energy related ^a	$C_{o(er)}$	V 0V 400 V V 0V		-	58	-	
Effective output capacitance, time related ^b	C _{o(tr)}	V _{DS} = 0 \	$V_{DS} = 0 \text{ V to } 480 \text{ V}, V_{GS} = 0 \text{ V}$		296	-	
Total gate charge	Qg			-	61	122	
Gate-source charge	Q_{gs}	V _{GS} = 10 V	$I_D = 8.5 \text{ A}, V_{DS} = 480 \text{ V}$	-	14	-	nC
Gate-drain charge	Q _{gd}	7		-	23	-	
Turn-on delay time	t _{d(on)}			-	22	44	
Rise time	t _r	$V_{DD} = 480 \text{ V}, I_{D} = 8.5 \text{ A},$ $V_{GS} = 10 \text{ V}, R_{g} = 9.1 \Omega$		-	24	48	ns
Turn-off delay time	t _{d(off)}			-	71	142	
Fall time	t _f			-	26	52	
Gate input resistance	R_g	f = 1 MHz, open drain		0.3	0.7	1.4	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	15	
Pulsed diode forward current	I _{SM}			-	-	45	- A
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 8.5 A, V _{GS} = 0 V		-	-	1.2	V
Reverse recovery time	t _{rr}	T _J = 25 °C, I _F = I _S = 8.5 A, dl/dt = 100 A/ μ s, V _R = 25 V		-	416	832	ns
Reverse recovery charge	Q _{rr}			-	6.4	12.8	μC
Reverse recovery current	I _{RRM}			-	27	-	A

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

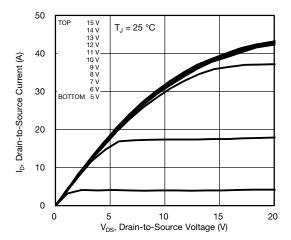


Fig. 1 - Typical Output Characteristics

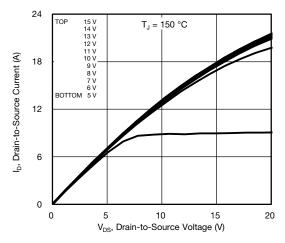


Fig. 2 - Typical Output Characteristics

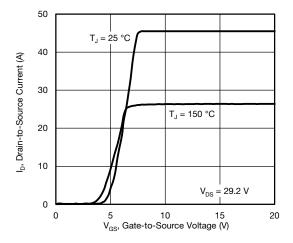


Fig. 3 - Typical Transfer Characteristics

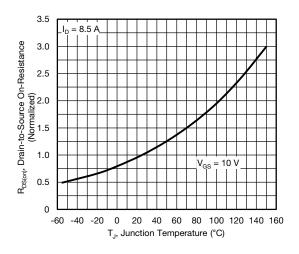


Fig. 4 - Normalized On-Resistance vs. Temperature

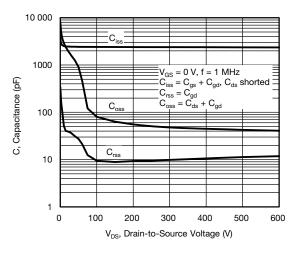


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

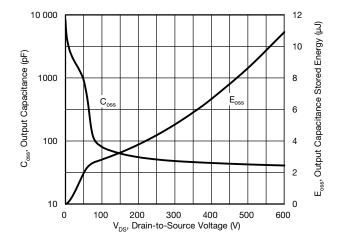


Fig. 6 - Coss and Eoss vs. VDS



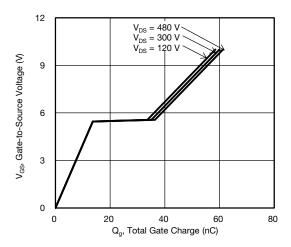


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

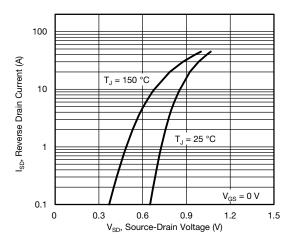


Fig. 8 - Typical Source-Drain Diode Forward Voltage

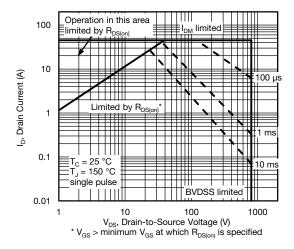


Fig. 9 - Maximum Safe Operating Area

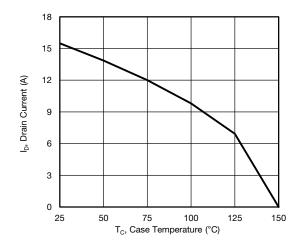


Fig. 10 - Maximum Drain Current vs. Case Temperature

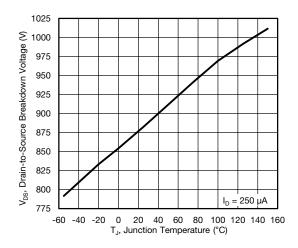


Fig. 11 - Temperature vs. Drain-to-Source Voltage



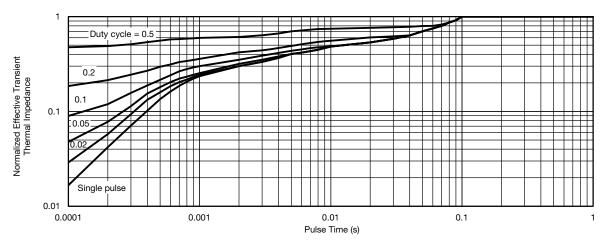


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

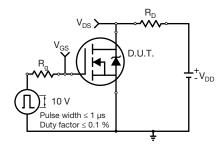


Fig. 13 - Switching Time Test Circuit

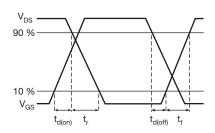


Fig. 14 - Switching Time Waveforms

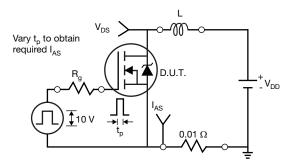


Fig. 15 - Unclamped Inductive Test Circuit

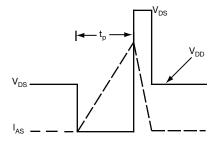


Fig. 16 - Unclamped Inductive Waveforms

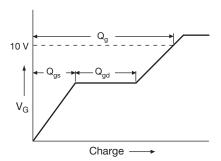


Fig. 17 - Basic Gate Charge Waveform

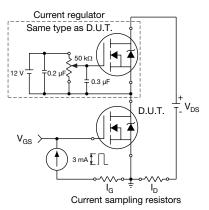
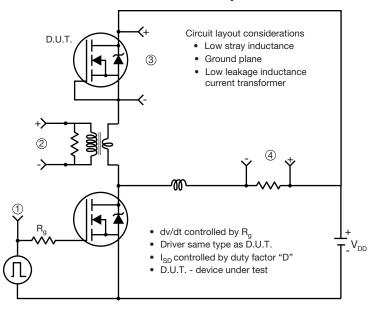


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit



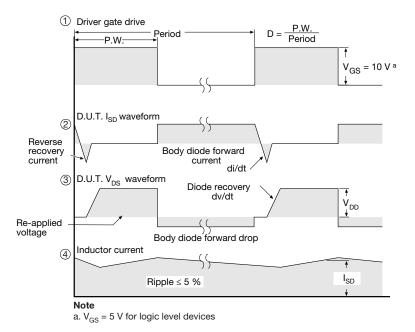
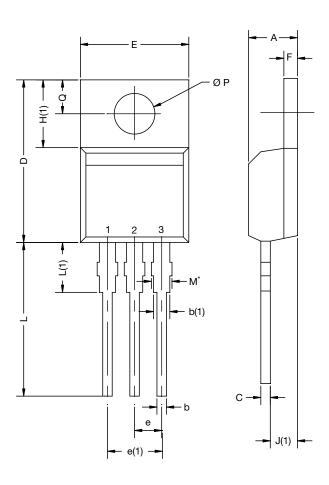


Fig. 19 - For N-Channel

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TO-220-1



DIM.	MILLIM	METERS	INC	HES
	MIN.	MAX.	MIN.	MAX.
Α	4.24	4.65	0.167	0.183
b	0.69	1.02	0.027	0.040
b(1)	1.14	1.78	0.045	0.070
С	0.36	0.61	0.014	0.024
D	14.33	15.85	0.564	0.624
Е	9.96	10.52	0.392	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.10	6.71	0.240	0.264
J(1)	2.41	2.92	0.095	0.115
L	13.36	14.40	0.526	0.567
L(1)	3.33	4.04	0.131	0.159
ØΡ	3.53	3.94	0.139	0.155
Q	2.54	3.00	0.100	0.118

Note

DWG: 6031

• $M^* = 0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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